

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4862221

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
BHARAT BHUSHAN	03/08/2018
JUAN BOON TAN	03/09/2018
YI JIANG	03/09/2018
DANNY PAK-CHUM SHUM	03/09/2018
WANBING YI	03/09/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	GLOBALFOUNDRIES SINGAPORE PTE. LTD.
<b>Street Address:</b>	60 WOODLANDS INDUSTRIAL PARK D STREET 2
<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	738406
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15917084
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)519-9958
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	7035199951
<b>Email:</b>	docket@dcpatent.com
<b>Correspondent Name:</b>	DITTHAVONG & STEINER P.C.
<b>Address Line 1:</b>	44 CANAL CENTER PLAZA
<b>Address Line 2:</b>	SUITE 322
<b>Address Line 4:</b>	ALEXANDRIA, VIRGINIA 22314
<b>ATTORNEY DOCKET NUMBER:</b>	P8842US00
<b>NAME OF SUBMITTER:</b>	KHOUANE DITTHAVONG
<b>SIGNATURE:</b>	/Khouane Ditthavong/
<b>DATE SIGNED:</b>	03/12/2018
<b>Total Attachments: 5</b>	

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**COMBINED DECLARATION and ASSIGNMENT (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)**

<b>Title of Invention</b>	<b>HIGH-DENSITY STT-MRAM WITH 3D ARRAYS OF MTJS IN MULTIPLE LEVELS OF INTERCONNECTS AND METHOD FOR PRODUCING THE SAME</b>
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**DECLARATION**

As the below named inventor, I hereby declare that:

This declaration is directed to:  The attached application, or  United States application or PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

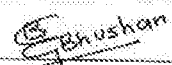
I have reviewed and understand the contents of the application and am aware of the duty to disclose to the US Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR § 1.56.

**ASSIGNMENT**

For good and valuable consideration, the receipt, sufficiency and adequacy of which are hereby acknowledged, I hereby sell, assign, transfer, to GLOBALFOUNDRIES Singapore Pte. Ltd. having a business address of 60 Woodlands Industrial Park D Street 2, Singapore, 738406, its successors and assigns, absolutely and forever, my entire right, title and interest in and to the invention listed above, together with the Application, any and all Patents that may issue in the United States and/or any foreign countries, and any reissues, re-examinations, renewals, continuations, continuation-in-parts, divisionals or extensions thereof that may be issued or granted, and all right, title and interest to the inventions contained in said Patents and Applications, for the United States and all foreign countries, and all the rights and privileges relating thereto including but not limited to the priority rights arising from said Applications, the right to recover and take all such proceedings as may be necessary for the recovery of damages or otherwise in respect of past, present and future infringement, and the right to apply for, take and maintain patents on said inventions.

**If any portion of this Combined Declaration or Assignment is held unenforceable, then remaining portions hereof shall nevertheless remain in full force and effect.**

**LEGAL NAME OF INVENTOR**

Inventor: Bharat BHUSHAN Date: Mar 08, 2018  
 Signature: 

**Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use an additional form for each additional inventor.**

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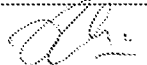
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**LEGAL NAME OF INVENTOR**

Inventor: Juan Boon TAN Date: 9 Mar 2018  
 Signature: 

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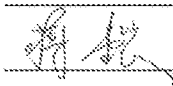
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**LEGAL NAME OF INVENTOR**

Inventor: YI JIANG Date: 2018.3.9  
 Signature: 

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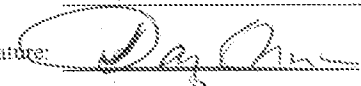
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**LEGAL NAME OF INVENTOR**

Inventor: Danny Pak-Chun SHUM

Date: 2019.3.9

Signature: 

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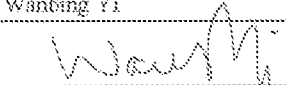
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**LEGAL NAME OF INVENTOR**

Inventor: Wanbing YI Date: 9-MAR-2018  
 Signature: 

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